SEMICONDUCTOR DEVICES FOR OPTICAL COMMUNICATION IN 1 µm BAND OF WAVELENGTH

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A summary is given of research on semiconductor devices for the long wavelength band used in optical communications. It is concluded that to utilize the advantages of this band, it is necessary to have a large scale multiple wavelength communication, along with optical cumulative circuits and optical exchangers.
1. Introduction

In the research on fiber optic communication which is achieving a remarkable degree of development in the recent years, systems for practical use have been developed for 0.8 µm band of wavelength, thus completing the so-called first generation. Now, the focus of research and development is about to start moving to the so-called long wavelength band with wavelengths of 1-1.8 µm, where loss of optic fiber is extremely small, which might be regarded as the second generation of fiber optic communication. The inception of this optical communication in the long wavelength band is the prediction that if the absorption by water is removed from silica fibers, the greater degree of reduction in loss could be achieved for longer wavelengths, based on determinations of optic fiber losses over the long wave length zone by Maurer and others [1], followed by the development of manufacturing of silica fibers by the CVD method [2]. At the same time, research on new semiconductor material with the width of exclusion zone of 1 µm has also been started [3-4]. Subsequently, in 1976, cooperative research by Japan Telecommunication Corporation and Fujikura Densen, Co., developed a revolutionary fiber with transmission loss of 0.5dB/Km at the wave length of 1.3 µm [15], which resulted in worldwide attention attracted to the optical communication devices of the second generation, such as the light source and

* Numbers in the margin indicate pagination in the foreign text.
optical wave detector for this wavelength band.

The characteristics of the second generation long wavelength optical communication device have been described in reference [16], but we would like to summarize them in our own way of thinking: (1) optical transmission with extremely small loss is possible, so that exceedingly long relay distance could be attained. The transmission loss of optical fibers is shown in Figure 1 (a). With a wavelength of 1.6 μm, a loss of 0.2dB/Km was achieved at the end of 1978 (Ibaraki Communication Laboratory, Japan Telecommunication Corporation [17].; (2) because of the small loss of 1dB/Km or less over a wide range of wavelengths from 1.1-1.8 μm, the multiplex wavelength system [18] in which a large number of different wavelengths is transmitted on a single fiber could be utilized, so that the high frequency of optical wave frequency could be used effectively; (3) as shown in Figure 1, the core diameter that fulfills the condition for unitary mode transmission of optical fibers could be taken at relatively large values; (4) the Rayleigh scattering which is one of the factors in optical loss in laser and optical circuits becomes smaller in the long wavelength zone, in proportion to $\lambda^{-4}$; (5) Garnet type materials for optical isolator become transparent above 1.2 μm, which was not easily achieved in the first generation (1). (In Figure 1 (c), optical absorptive losses against wave deviation at 45° rotation, necessary when materials such as YIG are used in an isolator [20], are shown as new performance index). Lastly, just to make an additional point, (6) over this range of wavelengths, the material scatter, which acts as one of the factors in limiting the range of transmission band of optical fibers, could be held within $\pm$ 3ps/Km (distance). A (width of wavelength) [21].

Furthermore, when wavelength increases, as could be seen from Figure 1 (a), transmission loss increases due to the effects
(a) Transmission loss of optical fibers,  
(b) Fiber core diameter of unified mode, 2a,  
(c) Loss constant to deviated wave surface rotation of 45° Faraday rotation device.

Figure 1. Characteristics of optical devices in long wavelength zone
specific infrared absorption due to molecular vibration of SiO₂ and GeO₂, which is a dopant. However, materials such as CsI which become transparent with longer wave lengths (0.01dB/Km or less), are being studied as optical guides for medical use [22]. Thus, optical communication in longer wavelength areas such as λ=2-10 μm, utilizing the advantages as noted in (3) and (4) above, is not impossible. However, with an increase in wavelength, the energy of photon hf (h: Planck's constant, f: frequency) decreases. At the wavelength of 10 μm, it is 0.12eV. On the other hand, thermal energy kT (k: Boltzmann constant, T: absolute temperature) is 0.03eV at 70°C, which is a high temperature in the field of communication, so that it becomes not negligible in comparison with the photon energy of long wavelengths. Thus, effects appear on optical detectors and on thermal characteristics of lasers. Accordingly, lasers and optical detectors based on principles different from those for the optical devices which were effective in the second and third generations become necessary, so that the area of λ>2 μm could be termed optical communication of the fourth generation.

In this article, semiconductor devices for the 1-1.8 μm band are discussed, but one should not forget the accumulation of basic research which led to the recognition of the excellent advantages of this wavelength band.

2. Lattice-adjusted four-dimensional semiconductor crystals.

2.1. Crystal formation and width of exclusion zone.

No two-dimensional semiconductor crystals with the width of exclusion zone corresponding to the 1 μm wave length band noted above, are available, so that it is necessary to use three or four dimensional crystals. However, for optical
semiconductor devices with high electric current density (~5kA/cm² μm) and high optical power output (~1 mW/μm²) activation such as semiconductor lasers and LEDs, and photodiodes for low noise optical detection, it is important to carry out adjustment of lattice constants between the base plate crystal used for crystal growth and the four-dimensional crystals that serve as the activated layers. For example, the lattice maladjustment between Ga As and Ga_{1-x}Al_{x}As (x=0.3-0.5) used in the GaAs system of semiconductor lasers is around 0.03-0.05%. On the other hand, four-dimensional mixed crystals consisting of four elements could alter the width of the exclusion zone greatly while perfect lattice adjustment with two dimensional crystals used as the basal plate is maintained. In Figure 2, the relationships between various two-dimensional crystals with lattice constants of four-dimensional crystals they form, and width of the exclusion zone are shown. For example, in Ga_{x}In_{1-x}As_yP_{1-y} with InP (a=5.8696Å) as the basal plate, changing of compositions along the abscissa enables changing of widths of the exclusion zone over the range of 0.75<E_g<1.35eV. As the mixed crystals corresponding to the so-called 1 μm band, the following could be considered [23]. Substances in the parentheses represent basal plates. With these, crystal growth is possible with lattice maladjustment of ±0.03% or below.

(1) \( \text{Ga}_{x}\text{In}_{1-x}\text{As}_y\text{P}_{1-y}(\text{InP}) : 0.92 < E_g < 1.67 \) μm

(2) \( \text{Ga}_{1-x}\text{Al}_x\text{As}_y\text{Sb}_{1-y}(\text{GaSb}) : 0.8 < E_g < 1.7 \) μm

(3) \( \text{Ga}_{x}\text{In}_{1-x}\text{As}_y\text{Sb}_{1-y}(\text{InSb}) : 1.68 < E_g < 2 \) μm

(4) \( \text{Ga}_{x}\text{In}_{1-x}\text{As}_y\text{Sb}_{1-y}(\text{GaSb}) : 1.8 < E_g < 2 \) μm

For the past 3 years, hetero-combination of the first system, that is Ga_{x}In_{1-x}As_yP_{1-y} with InP as the basal plate, and InP have been studied mainly because of the excellence in crystal formation for use as the material for lasers and photodiodes.
Thus, the conditions of crystal growth of this system are summarized below.

2.2 Crystal growth in GaInAsP/InP.

The cross sectional structure of a wafer for a semiconductor laser with GaInAsP as the laser activation layer and InP as the clad layer, is as follows (also, see Figure 6): First, n-type InP is placed over the InP basal plate, over which GaInAsP without doping, and the p-type InP layer as the clad layer are superimposed [24]. At times, a p-type GaInAsP layer is placed over as a cap layer, to form excellent ohmic electrodes [25]. For measurements of the cross section of the activation layer, the cleaned cross section is stain-etched with a mixture solution of K₃Fe(OH)₆ and KOH, and the surface is measured by SEM.

In order to obtain the multilayered thin film wafer as
described above, various methods such as vapor phase epitaxy, liquid phase epitaxy, and molecular beam epitaxy have been tried. Of these, the liquid phase epitaxy method of crystal growth is most popularly used, and renders high quality wafers for lasers. Thus, this method is summarized here. To grow a multilayered thin film of Ga\textsubscript{x}In\textsubscript{1-x}As\textsubscript{y}P\textsubscript{1-y} by the liquid phase epitaxy method, solid phase extraction from a supercooled solution using a slide board, similar to a GaAlAs laser, is utilized. Usually, In is used as the solvent, and GaAs, InAs, and InP as the sources for Ga, As, and P. The deviation extraction coefficient \( k_N = \frac{2X^s_N}{X^l_N} \) is used as a parameter to show the proportions of respective components of the solid phase four dimensional crystal \( x^s_N(N=Ga, In, As, P) \) extracted from the liquid phase components \( x^l_N \) in the solvent. With specific components \( x=X_{Ga}s, y=X_{As}s \), \( k_N \) takes different values. In order to understand the conditions for crystal growth, it is necessary to construct phase diagrams centered around knowing \( k_N \). Several studies have been carried out over the past 2-3 years in this direction [6, 9, 24-33], elucidating the conditions for crystal growth of GaInAsP. From these, experimentally obtained liquid phase components \( x^l_N \), with supercooling method with temperature of starting crystal growth of 630-650°, are shown in Figure 3. From the figure, the amount of source crystals to be dissolved in the In solution could be determined. The studies cited here are recent ones based on systematic experiments, but it should be remembered that in the early, pioneering studies, a great deal of work was expended in determining the amounts of source crystals to be dissolved. As could be seen from the figure, some differences are noted due to temperatures for starting of crystal growth, and method of cooling. Scattering seen in similar systematic studies may be due to errors in weighing of source crystals as well as error in measuring of solid phase component ratio.
Based on the liquid phase components as described above, GaInAsP crystals with good lattice adjustment with the InP basal plate should grow, but since there are some differences in absolute temperatures of the basal plate and solution caused by different furnaces used, to achieve complete lattice adjustment and select the oscillating wavelength exactly as designed, fine tuning is carried out by slightly changing concentrations of Ga [34] or As [35]. Theoretically, it is possible to make $\Delta a$ be zero. The separation capability of the x-ray diffraction meter in general use is about $\pm 0.03\%$, so that the degree of
adjustability has the limitation of this degree. When the lattice of a four-dimensional crystal is not adjusted with that of InP, distortion of the lattice is seen mainly in the direction perpendicular to the plane of the basal plate, and virtually no changes are seen in the direction parallel to that plane [34]. Thus, it is considered that if the direction of the plane chosen for x-ray diffraction is taken in the direction perpendicular to the basal plate such as (400), the degree of maladjustment could be measured quite well.

In terms of the direction of the plane of the InP basal plate used in crystal growth, in the early phase of research, the use of the (100) plane resulted in the formation of small holes of 1 μm size, and poor reproducibility, so that the (111)B plane has mainly been used. However, since Hsieh [36], and Itaya and the authors [37] successfully constructed semiconductor lasers of equally good performance level, using the (100) plane as the basal plate, the (100) plane is now being used frequently. The advantages of the (100) plane include the ease of cleavage, ease of crystal growth in terms of selective crystal growth, etching and lattice adjustment, as well as the fact that technology accumulated by GaAs method could be utilized for forming into various shapes by etching.

Also, the relationship between the solid phase component ratios \( x=X_{GaS} \) and \( y=X_{AsS} \) of four-dimensional crystals formed with lattice adjustment, and width of the exclusion band \( E_g \) are extremely important in practical use. These are determined by substituting experimental values into Vegard's law. Using a recent report [38], the relationship between \( x \) and \( y \) in condition of lattice adjustment could be expressed as

\[
x = \frac{0.466 \, y}{1.03 - 0.03 \, y} \quad (0 \leq x \leq 1)
\]

(2)

and the width of the exclusion band \( E_g \) could be given by the
solid phase composition ratio $y$ of As, thus:

$$E_g(y) = 1.35 - 0.72y + 0.12y^2 \text{ (eV)}$$  \hspace{1cm} (3)$$

In Figure 4, $E_g$ or the corresponding wavelength $x_g$, are shown.

3. Semiconductor lasers

For semiconductor lasers of 1-1.7 \( \mu \text{m} \) band, the structure and characteristics, mainly centered on the GaInAsP/InP system, are summarized.

3.1. Area of oscillating wavelength and threshold electric current

The width of the exclusion band of Ga$_x$ In$_{1-x}$As$_y$ P$_{1-y}$ could be expressed as an approximation by the equation (3). The range of possible wavelengths includes 0.92 < $\lambda_g$ < 1.67 \( \mu \text{m} \). A semiconductor laser of double hetero structure with InP as the clad layer, as shown in Figure 6, has been materialized over the range of wavelengths 1.1 < $\lambda$ < 1.67 \( \mu \text{m} \).

In Figure 5, threshold electric current density per unit activated layers $J_{th/d}$ of the Ga$_x$ In$_{1-x}$As$_y$ P$_{1-y}$/InP laser is shown. With liquid phase epitaxy, about 4.5 kA/cm$^2$ \( \mu \text{m} \) have been achieved for 1.1 < $\lambda$ < 1.55 \( \mu \text{m} \) [24, 25, 33, 35, 39, 41]. For the maximum wavelengths of $x=0.466$, $y=1$, with the liquid phase method, the density is about 12 kA/cm$^2$ \( \mu \text{m} \) [42] for the GaInAsP/GaInAs/InP structure, and 8 kA/cm$^2$ \( \mu \text{m} \) [33] for the InP/GaInAsp/GaInAs/InP structure. However, with the molecular beam method, the value is lowered to the neighborhood of 5 kA/cm$^2$ \( \mu \text{m} \) [43]. Also, for lasers of 1.2 < $\lambda$ < 1.4 \( \mu \text{m} \) made by gaseous phase epitaxy, about 6 kA/cm$^2$ \( \mu \text{m} \) has been achieved [38], demonstrating the high quality crystals equivalent to those made by the liquid phase method. Accordingly, it appears possible to manufacture
Figure 4. Width of exclusion band $E_g$ against solid phase component ration $x = X_{GaS}$, $y = X_{AsS}$.

Figure 5. Threshold electric current density $J_{th}/d$ that corresponds to the thickness of unit activated layer of GaInAsP/InP laser. In terms of carrier concentration, $5kA/cm^2 \mu m$ corresponds to about $3 \times 10^{16}/cm^3$. 
lasers with low threshold electric current over almost all areas of components of this four-dimensional material.

Variations of threshold electric current density $J_{th}$ in terms of thickness of the activated laser $d$ have been studied [41, 45, 46]. At present, the minimum value is present in the neighborhood of $d=0.1\sim0.2 \, \mu m$, with $J_{th}=1 \, [45] \sim 2 kA/cm^2 [41]$. A low value such as 0.78 kA/cm$^2$ for $d=0.13 \, \mu m$ has been recorded. Usually, the activated layer is left without doping on purpose, but since Zn that diffuses fast is frequently used as a dopant in the p type InP layer of layer III, diffusion into the activated layer during crystal growth could sometimes occur, precluding normal hetero combination. Especially with a thin activated layer (less than 0.1 $\mu m$), the selection of Zn concentration in accordance with value of $d$ could lead to the reduction of threshold electric current [45]. Cd has also been tried as a dopant [43].

It is desirable to minimize impurity concentrations in the activated layer. The reason for this is that the yield difference in the vertical mode increases, and hole burning becomes less likely to occur [47], making the single vertical mode oscillation at the time of CW quite easy.

The index of refraction of GaInAsP for $\lambda=1.3 \, \mu m$ is $n=3.5$ [48, 66], and that for InP is $n=3.23$ [49]. It follows that the difference in specific refraction index, which serves as an index for sealing-in effect of light, $\Delta=(n_1-n_2)/n_1=717\%$. This, in comparison to $x=0.4$ for Ga$_{1-x}$Al$_x$As/GaAs, is quite large.

3.2. Structure of stripe lasers

With semiconductor lasers, it is customary to form a stripe type activated layer with 2-15 $\mu m$ width, in order to achieve the stabilization of horizontal mode, the improvement of
linearity of the electric current to light power output characteristics, and the unification of vertical mode. Methods of construction of several types of stripe laser in the GaAs/GaAlAs laser have already been established [50]. Similar stripe construction has been tried for the GaInAsP/InP laser. Also, entirely new types have been proposed.

An example of an electrode stripe, which is one of the frequently used stripe constructions, is shown in Figure 6. The p+ layer of GaInAsP [25] is often provided in order to improve ohmic contact with the anode. Examples of other stripe-type structures are shown in Figure 7. Of these, (a)-(f) possess the optical wave conduction function in the horizontal direction as well by difference in refractory rates, so that the horizontal mode is stable when electric current is increased and vertical mode is also highly likely to be unified. Figure 8 shows the spectrum of the electrode stripe type GaInAsP/InP laser and examples of measurements of electric current versus power output [54].

Typical action parameters of the GaInAsP/InP stripe lasers include: voltage = 0.9V, electric current 100-200mA, resistance 1-2Ω, power output = several mW. Heretofore, experiments have been performed mainly with the system of λ=1.3 μm, but approximately similar characteristics could be expected for 1.1-1.55 μm. For the 1.6 μm band, further studies are needed for areas such as improvements in methods of crystal growth.

3.3. Thermal characteristics

A unique characteristic of semiconductor lasers is that with an increase in the electric current entering, a threshold value is reached as shown in Figure 8(b). For higher electric current, efficiency of luminescence becomes exceedingly great. If threshold electric current density at temperatures T' and T
Figure 6. Commonly used electrode stripe or planar stripe type GaInAsP/In laser. (In practical use, this is frequently mounted with the anode facing downward).

1 - light; 2 - cathode; 3 - diffusion; 4 - anode; 5 - stripe; 6 - surface; 7 - basal plate

Figure 7. Examples of Cross Sectional Structure of Stripe Type GaInAsP/InP Lasers

* activated area
are designated respectively as $J_{th}(T')$ and $J_{th}(t)$, then their relationship could be expressed as:

$$J_{th}(T) = J_{th}(T') \exp\left(\frac{(T - T')}{T_0}\right)$$  \hspace{2cm} (4)

Here, $T$ is the characteristic temperature, which is the temperature where $J_{th}$ becomes $e$ times as great when thermal elevation $T - T'$ is $T_0$.

There are two characteristic experimental facts related to the thermal characteristics of threshold values for GaInAsP/InP lasers. The first is the rapid decrease in $T_0$ in the neighborhood of room temperature [35, 57]. This is small, for example, in comparison with 100-120K for GaAs/GaAlAs laser, and improvements are needed for practical use. For high temperatures above room temperature, leakage of electric current for the
hetero barrier is also possible, causing further increases in the threshold value. This effect has been measured by lasers with differing hetero barriers made by the vapor phase growth method. Figure 9 shows the ratio of the increase of threshold electric current density from 22°C of GaInAsP/InP lasers of differing oscillation wavelengths at 70°C [44]. It could be seen that the shorter the wavelength (that is, smaller hetero barrier), the poorer the characteristic temperature. However, at $\lambda > 1.3 \, \mu m$, the characteristic temperature could be converged to the level equal to that for a GaInAs three-dimensional laser.

On the other hand, the temperature fluctuation of oscillating wavelengths is about $3.5 - 4 \, \AA/K$ [35, 53, 58], which is somewhat greater than that for GaAlAs lasers. However, with special constructions such as distribution Bragg reflection type (DBR), it becomes $0.7 - 0.8 \, \AA/K$ [48].

3.4. Tests for durability of devices

The most important factor, above all else, for optical devices is their reliability. This newly developed material also has been studied for its durability from the inception. Fortunately, with GaInAsP/InP lasers, it was possible to find material with relatively long durability from the beginning of research, and it was felt that the material is of quite good quality. In addition, despite the high value of $10^4 - 10^8 / \text{cm}^2$ ($\approx 10^3 / \text{cm}^2$ with GaAlAs system) of the transposition density of InP crystals which are base plates, as etch pit density, devices with long durability have been made. This is appreciably different from the GaAlAs system. Continuous action at room temperature exceeding 10,000 hours with GaInAsP/InP lasers for 1.3 $\mu m$ made with the (100) basal plate using the liquid phase method has been confirmed [51]. The spectrum shown in Figure 8 is one
Figure 9. Degree of elevation of threshold value of GaInAsP/InP laser, by vapor phase growth method [44]

Figure 10. Direct modulation characteristics of GaInAsP/InP laser (λ=1.3 μm) [68]

Figure 11. Pulse modulation wave form of GaInAsP/InP (λ=1.3 μm) (detected by GeAPD [made by Fujitsu])
after 7,800 hours. Also, with GaInAsP/InP lasers made by the vapor phase method, continuous testing at room temperature for 1,500 hours has been carried out [44], as well as high temperature acceleration tests at 70°C.

In the future, research for devices with greater reliability will continue through the elucidation of the mechanism of deterioration which is thought to be somewhat different from that of GaAlAs, development of InP basal plate with small amount of transposition [59], improvement of electrodes, and protection of mirror surfaces. Also, the material is thought to have potential for such improvements.

3.5. Modulation and device characteristics

The length of recombination durability of the small number of carriers injected to the activation layer, $\tau_s$, is an important parameter in determining the upper limit of the direct modulation frequency, so that interest has been focused on these new four-dimensional crystals from the inception. The attempted methods for the determination of this parameter include; (1) the method of measurement by elevations of pulse amplitude and threshold value when narrow width pulse electric current is injected [37], and (2) the method of measurement by the dependency of resonant frequency on injected electric current [60, 61], and the method by computing from the delay in oscillation time with pulse excitation of electric current with fast standing up time [60, 61]. Compiling these results, it has been demonstrated that $\tau_s=2-3$ns for a laser of $\lambda=1.2-1.3$ μm, and the temperature dependency of $\tau_s$ resembles that of a Ga As laser [53].

From the foregoing, it could be expected that direct modulation to several GHz is possible with GaInAsP/InP lasers, similar to Ga As lasers [60], and actual experiments on high speed pulse
modulation [62] and measurements of frequency dependency on the degree of modulation [63] have been carried out. Figure 10 shows the degree of modulation when a laser with $\lambda=1.3\ \mu\text{m}$ is sine wave modulated. It shows the band area of over 20GHz for $I/I_{th}=1.3$, confirming the prediction from the value of $\tau_5$. Figure 11 is an example of the optical wave form when pulse modulation is carried out, showing that pulse amplitude of around 250ps is obtained.

As has been shown in Figure 6, the expansion of the light beam of a semiconductor laser is great in the direction perpendicular to the activated layer. This angle of expansion $\Delta \theta$ is inversely proportional to the spot size of the resonant mode, so that by making the thickness of the activated layer exceedingly small, the spot size could be increased, and $\Delta \theta$ decreased. When $d=0.05\mu\text{m}$, about $23^\circ$ is obtained [45], and even when $d=0.13\ \mu\text{m}$, it is about $40^\circ$, which is equal to or less than for GaAs laser.

3.6. Development of new methods of manufacturing, material and models

For the method of manufacturing wafers for GaInAsP/InP lasers, the liquid phase epitaxy noted above is being firmly established with the completion of phase diagram almost attained. With wavelength band of 1.1-1.15 $\mu\text{m}$, wafers with threshold electric current density of 4.5 A/cm$^2$ $\mu\text{m}$ could be constructed. The minimal threshold value is about 1kA/cm$^2$ for thickness of activated layer $d=0.1-0.2\ \mu\text{m}$. On the other hand, basic research on construction of wafers by vapor phase epitaxy has been carried out, and at the International Convention on Semiconductor Lasers at the end of October, 1978, the first report of successful oscillation with a GaInAsP/InP laser was given, according to which $J_{th}=7kA/cm^2$ or thereabouts, thus demonstrating wafers comparable to
those made by the liquid phase method [44]. Since large size wafers for mass production could be constructed, and good control of film thickness for uses such as optical cumulative circuits could be attained, this is an exceedingly noteworthy method of production.

With $\text{Ga}_x\text{In}_{1-x}\text{As}_y\text{P}_{1-y}$, if $y=1$, then GaInAs that corresponds to the maximum wavelength of $\lambda=1.65$ μm could be obtained. This is a three-dimensional crystal without containing P. When InP is grown on it for the clad layer, melt back develops, making crystal growth difficult. This has also been tried with the liquid phase method [33,42], with threshold electric current density of around $8\text{kA/cm}^2$ μm. However, with molecular beam epitaxy, the possibility of constructing wafers with $5\text{kA/cm}^2$ μm has been demonstrated [43]; aside from the practicability of this method of construction, it is noteworthy that lasers of fairly uniform performance level could be constructed for the entire wavelength of $\text{Ga}_x\text{In}_{1-x}\text{As}_y\text{P}$.

As another material, GaAlAsSb/GaSb lasers with low threshold values have been reported. As noted previously, with $\text{Ga}_{1-x}\text{Al}_x\text{As}_y\text{Sb}_{1-y}$, luminescence is possible for the range of $0.8<\lambda<1.7$ μm. However, recently those with low threshold values of electric current density of $1\text{kA/cm}^2$ or less and range of 1.25 - 1.4 μm have been constructed [64]; also, a $\text{Ga}_x\text{In}_{1-x}\text{As}_y\text{Sb}_{1-y}$/GaSb (basal plate GaSb) laser has been constructed, obtaining $\lambda=1.9$ μm, $J_{th}=900\text{A/cm}^2$ at 77K [65].

For construction aimed at mode stabilization, various types of embedded stripe construction as shown in Figure 7 have been proposed and tested, and it is likely that the development of lasers with stable horizontal modes, with wave conduction capability by different rates of refraction, would proceed. Also, as a method of construction aimed at the unification and stabilization of the vertical mode, a distribution Bragg reflector (DBR) laser that utilizes the primary diffractive lattice has been constructed on a trial basis [66], with which detailed
studies on thermal characteristics have been carried out. The optical cumulative circuit with InP as the basal plate is considered by the authors to increase its importance in optical circuit technology of the future. To serve as a basis of this technique, studies on chemical etching methods and on identification of (011) and (011) directions with (100) InP basal plate have been carried out.

4. Luminescent diodes

Development of luminescent diodes (LED) of 1 μm band has been started since around 1977. As with semiconductor lasers, many of these diodes have the double hetero structure of Ga\textsubscript{x}In\textsubscript{1-x} As\textsubscript{y}P\textsubscript{1-y}/InP [29, 69, 72]. The type of wafer is basically similar to that for lasers, as shown in Figure 6. Figure 12 shows an example of the structure of a plane luminescent type GaInAsP/InP LED. Since the InP basal plate is transparent for the luminescent wavelength, it could be used as a window without modification. Frequently the activated layer in these diodes is not covered with doping on purpose. Power output is 1 [70] - 3mW [71], external quantum efficiency is 1 [70] - 3% [71]. Diodes with a wavelength band of 1.1 [68] - 1.5 μm [29] have been constructed, and half-value widths of the luminescent spectra Δλ are about 1,000-1,200Å. The relative value Δλ/λ=0.07-0.08 is appreciably greater than 0.04-0.05 for GaAs LED. Modulation characteristics and combination with optical fibers have also been studied, and the cutoff frequency has been determined to be 60-70MHz [69]. A method to make the power output window into a monolithic, convex lens shape has also been proposed [72].

5. Optical detector

The sensitivity of the Si photodiode used in the 0.85 μm wave length band deteriorates markedly for wavelengths greater
than 1 µm. It is inevitable, theoretically as well, that in the longer wavelength band, effects of noise become greater. Heretofore, a Ge photodiode has been used as the optical detector corresponding to this wavelength band, but there are problems of dark electric current and loud excessive noise, so that three and four-dimensional crystals have begun to be studied as photodiode material with low noise and fast height elevation close to 50 ps [73].

![Diagram of GaInAsP/InP luminescent diode](image)

**Figure 12.** Example of construction of GaInAsP/InP luminescent diode.

![Graph of quantum efficiency vs. wavelength](image)

**Figure 13.** Sensitivity of photodiode for 1 µm band.
Figure 13 shows wavelength sensitivity of photodiodes made of Ge [74] and Ga$_{0.47}$ In$_{0.53}$ As [75, 76]. The sensitivity of Ge is at around 1.5 µm, and avalanche photodiodes (APD) and P-i-n construction photodiodes have been manufactured for practical use. However, as shown in Figure 14, dark electric current is $10^{-4}$ (A/cm$^2$), which is exceedingly greater than $2.5 \times 10^{-9}$ (A/cm$^2$) for Si [75]. Also, since ionization coefficients for electrons and positive hole are approximately equal, excess noise at the time of avalanche amplification is great.

Four dimension crystals used in lasers as well, such as Ga$_x$ In$_{1-x}$ As$_y$ P$_{1-y}$ and three dimension crystals Ga$_{0.47}$ In$_{0.53}$ As, have been studies as the material for optical detectors [73, 75-82]. Figure 13 shows quantum efficiency of a Ga$_{0.47}$ In$_{0.53}$ As photodiode, which has sensitivity to the largest wavelength, among all the materials noted above. There is a report that with this material, dark electric current could be reduced to around $4-7 \times 10^{-6}$ (A/cm$^2$) [75], appreciably such than that for Ge. Also, it has been said that the ionization coefficients
at the time of avalanche amplification are greater for electrons than for positive holes [77]. If four-dimensional crystals with χ<0.46 are used, the width of the exclusion band increases and the maximum sensitivity moves to the short wave side [76].

Research on optical detectors for larger wavelengths, especially on APD, has just begun. It appears that GaInAs becomes low noise, but there are still some problems such as large transposition density of InP used for the basal plate.

At high speed, effects of dark electric current are small. With 32M bit/s PCM and when dark electric current is 100 nA, the deterioration of reception electric power of GeAPD is 4.5dB [16], so that requirements are somewhat less rigorous for the optical wave detector with high speed PCM. Ge has a long history in crystallization and economical potentials, so that it is being re-evaluated as a photodiode for long-wave optical detectors suitable for practical use. At least Ge photodiode could be used in the optical detector for longer wavelengths. Also, high performance detectors appear to be possible by the use of new materials such as GaInAs. Thus, the future for the optical detector for the 1 μm band is promising.

6. Conclusion

In this commentary, we summarize the state of research thus far on semiconductor devices for the 1-1.8 μm band, the so-called long wavelength band, used in optical communication, which currently is attracting attention. In this wavelength band, because of the characteristics of optical fibers that serve as the route of transmission, semiconductor laser materials that serve as the light source were developed first, followed by the study of the optical detector. This sequence is the reverse of that for the 0.85 μm band. However, the exceedingly low transmission loss of 0.2 dB/km attracted a large number of researchers to make
efforts in the development of optical devices, so that at present, devices that could be considered as systems are being materialized. Thus, with GaInAsP/InP, long durability devices as semiconductor lasers with λ=1.3 μm have been constructed, and the same material may be able to be utilized for 1.1-1.67 μm. (After the completion of this text and while waiting for printing, CW operation at room temperature of a 1.5-1.6 μm band laser has been achieved successfully by KDD, Telecommunication Corporation, and Tokyo Engineering University). On the other hand, it is inevitable that the optical detector becomes high noise, but this is not detrimental for optical transmission. Optical isolators for long wavelengths have been constructed [20], and long-distance transmission experiments over 10 km [83, 85] and 50 km [84] have been carried out; thus photocommunication of the second generation appears to be able to be established on appreciably good balance of devices.

However, in order to really utilize advantages of the long wavelength band, it is necessary to have a large-scale multiple wavelength communication, along with its requirements such as optical cumulative circuits and optical exchangers. When these are well studied, the dawn of the third generation of optical communication will become visible. Deep appreciation is extended to those who provided their valuable research findings.
REFERENCES


10. Takeda, et al., "Liquid phase epitaxial growth of In_{1-x}Ga_x As on the InP basal plate", Spring Joint Lecture Session of Societies on Applied Physics, 2a-E-9 (April 1975)


12. Ota, et al., "Luminescence characteristics of In_{1-x}Ga_x As diode and LASING", Spring Joint Lecture Session of Societies on Applied Physics, 1a-C-1 (April 1975)


16. Kumira, Daikoky, "Methods of optical transmission in the long wavelength, low loss band", Shingakushi 60; 12, p. 1379 (December 1977)


47.


49. For example, "Chemical compound semiconductor devices", Nippon Sangyo Gijutsu Shinko Kyokai, ed., (1973)

50. For example, Suehatsu, Iga, "Introduction to optical fiber communicator", Ohm-sha, publishers, (1978)


67. Uebayashi, et al., "Chemical etching of GaInAsP/InP with an optical cumulative circuit as the objective" Shingaku Gihoh, OQE 78-110 (1978)


82. Ito, M., Kaneda, T., Nakajima, K. Toyoma, Y., Yamaoka, T. and Kotani, T.: "Impact ionization ratio in In0.73Ga0.27As0.52P0.48", Electron. Lett. 14, 14, p 418 (July 1978)
